

AD-A091 958

TEXAS UNIV AT AUSTIN DEPT OF CHEMISTRY
ON THE ROLE OF SURFACE STATES IN SEMICONDUCTOR ELECTRODE PHOTOE-ETC(U)
OCT 80 A J BARD, F F FAN, A S GIODA
F/G 20/12
N00014-78-C-0592
NL

UNCLASSIFIED

TR-13

100
200

END

DATE

FILED

84

DTIC

AD A091958

LEVEL

OFFICE OF NAVAL RESEARCH

Contract N00014-78-C-0592

Task No. NR 051-693

TECHNICAL REPORT No.13

12

On The Role of Surface States in
Semiconductor Electrode
Photoelectrochemical Cells

by

Allen J. Bard, Fu-Ren F. Fan, Alberto S. Gioda,

G. Nagasubramanian and Henry S. White

Prepared for Publication

in

Faraday Transactions

DTIC
ELECTE
NOV 18 1980
S C D

The University of Texas at Austin
Department of Chemistry
Austin, Texas 78712

October 27, 1980

Reproduction in whole or in part is permitted for
any purpose of the United States Government.

This document has been approved for public release
and sale; its distribution is unlimited.

BDC FILE COPY

80 11 13 005

behaviour will be described. The effect of the surface pretreatment on the photoelectrochemical behaviour of p-GaAs and n-WSe₂ will be demonstrated.

Accession For	
NTIS GRA&I	<input checked="checked" type="checkbox"/>
DTIC TAB	<input type="checkbox"/>
Unannounced	<input type="checkbox"/>
Justification	
By	
Distribution/	
Availability Codes	
Dist	Special
A	

Unclassified

corrected
copy for file

70/1

On the Role of Surface States in Semiconductor Electrode Photoelectrochemical Cells

By

ALLEN J. BARD, FU-REN F. FAN, ALBERTO S. GIODA,
G. NAGASUBRAMANIAN AND HENRY S. WHITE

Department of Chemistry, The University of Texas at Austin,
Austin, Texas 78712, U.S.A.

Received 6th May, 1980

Surface states that occur at the semiconductor-liquid interface play an important role in the behaviour of that interface and affect the efficiency of photoelectrochemical solar devices. The nature of such states and evidence for their existence will be briefly reviewed. Their role in dark electron transfer reactions for redox couples with energies within the band-gap region and in mediating surface recombinations will be discussed. The importance of Fermi level pinning by surface states at moderate densities in GaAs and Si in controlling the open-circuit photovoltage and the observed electrochemical behaviour will be described. The effect of the surface pretreatment on the photoelectrochemical behaviour of p-GaAs and n-WSe₂ will be demonstrated.

In many ways the development of models for the semiconductor-liquid interface has paralleled that for the metal-semiconductor (M/SC) junction. The earliest models of M/SC junctions (Schottky barriers) by Schottky¹ and Mott² proposed a barrier equal to the difference in work functions between the metal and the semiconductor forming the contact. Subsequent experimental studies, however, showed considerable deviations from the predicted behaviour and the suggestion was put forth³ that surface states at the interface play an important role in determining the barrier height. Many theoretical and experimental studies have subsequently demonstrated the existence of such states and their effects on the junction characteristics. [See, for example ref. (4), (5) and references therein.] In a similar way the barrier at the semiconductor-solution interface has often been taken to be the difference between the flat-band potential of the semiconductor, V_{fb} , and the redox potential of a solution couple, V_{redox} , although as early as 1959 the importance of surface states in determining the potential distribution at this interface was indicated.⁶ It now appears clear that the behaviour of semiconductor electrodes is critically dependent upon the nature of the electrode surface and that the ideal model involving a state-free band gap is rarely applicable.

For the purposes of this paper surface states will be taken to mean surface electronic energy levels with energies different from the allowed levels in the bulk semiconductor. They may be states which arise because the lattice is terminated ("dangling bonds" or "intrinsic surface states"), because of lattice defects, vacancies or differences between the surface composition and that of the bulk, or because of adsorption of electron acceptor or donor species ("impurity states") which may act as surface states themselves or induce defect states in the semiconductor material. The number, distribution and energies of the surface states may depend not only upon the type of material employed and the crystal face exposed, but also upon the composition of the solution phase and the nature of the surface pretreatment before the junction is formed.

Surface states can play an important role in the behaviour of semiconductor electrodes. Dark redox processes of couples with energies located in the gap region may be promoted by such states. Under these circumstances the states may also behave as recombination centres and lead to decreased quantum efficiencies in photoelectrochemical (PEC) cells. A high density of these levels may lead to "Fermi level pinning" in which the observed photopotential becomes independent of the redox potential of the solution couple and photoprocesses are observed for couples whose energy levels apparently lie well outside the band-gap region (as determined by measurements made in the absence of the redox couple).⁷⁻⁹ Surface states may also play a role in the catalysis of electron-transfer reactions at the semiconductor electrode surface, in the quenching of spectral sensitization processes by dye layers, and in the photodecomposition reactions of the semiconductors. In this paper we discuss and give several examples of surface state effects in PEC cells and demonstrate that surface treatments of the semiconductor can be significant factors in the behaviour of these electrodes.

EXPERIMENTAL

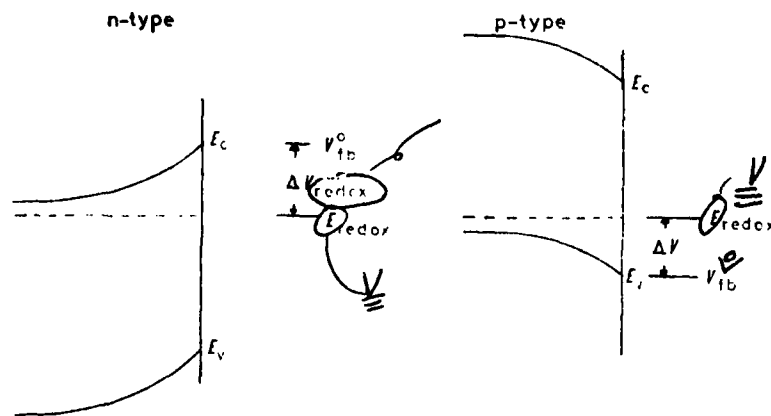
The sources of the semiconductor materials (all single crystals), the method of mounting and producing ohmic contacts, and the apparatus used in the measurements have been previously described.⁹⁻¹¹ The electrodes were illuminated with either a 450 W Xe lamp with suitable filters or a 1.6 mW He-Ne laser.

RESULTS AND DISCUSSION

FERMI LEVEL PINNING BY SURFACE STATES

PRINCIPLES

The qualitative and quantitative aspects of Fermi level pinning at the semiconductor-solution interface have been discussed in some detail,⁷⁻⁹ so that only the basic principles will be reviewed here. The model for the surface state-free semiconductor function can be represented as shown in scheme 1.^{12,13} The flat-band potential, V_{fb} , measured in a solution in the absence of a redox couple (V_{fb}^0), corresponds fairly closely to the energy of the conduction band edge (E_c) in an n-type semiconductor or to the valence band edge (E_v) in a p-type material. At V_{fb} in the absence of specific adsorption, the potential drop across the Helmholtz layer, $\Delta\phi_H$, corresponds to that attributable to oriented dipoles at the interface, V_d , while the potential drop across the



SCHEME 1

space charge region of the semiconductor, $\Delta\phi_{sc}$, is zero. (In all cases we assume a reasonably concentrated electrolyte so that the potential drop across the diffuse double layer can be neglected.) When the potential difference between the bulk semiconductor and the solution is varied either by application of an external potential or by introduction of an appropriate redox couple (located at $E_{redox} = -eV_{redox}$) in solution, $\Delta\phi_H$ remains largely unchanged while $\Delta\phi_{sc}$ essentially equals that of the applied potential (assuming no specific adsorption of the redox couple and no change in V_d). This is the basis for the usual model in which the band edges are said to remain fixed [i.e., $\Delta(\Delta\phi_H) \approx 0$] and in which the open-circuit photopotential (ΔV) under high illumination intensities is

$$\Delta V = |V_{fb} - V_{redox}|. \quad (1)$$

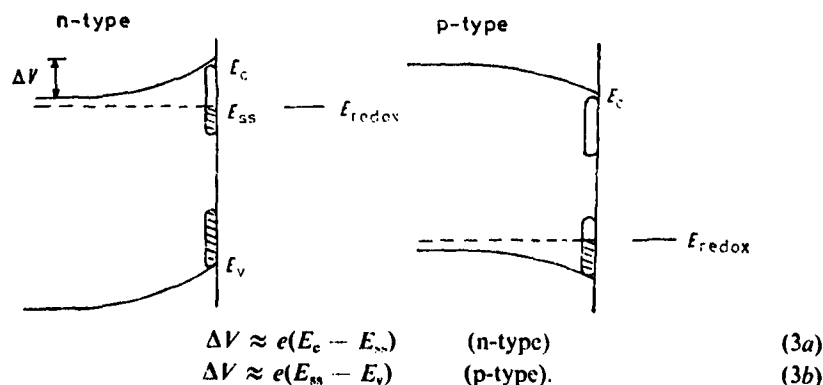
For couples with energies outside of the band gap, no photoresponse is expected. Eqn (1) is the basis for the selection of redox couples with potentials corresponding to energies near the valence band edge (for n-type) or near the conduction band edge (for p-type) to maximize the output photovoltage of a PEC cell.

The flat-band potential will be shifted by specific adsorption of ions, since the potential drop across the Helmholtz layer in the presence of surface charge, q_s , is given by

$$\Delta\phi_H = \frac{q_s}{C_H} + V_d = \frac{q_s}{\epsilon\epsilon_0/d} + V_d \quad (2)$$

where C_H is the Helmholtz layer capacitance, ϵ is the dielectric constant, ϵ_0 the permittivity of free space, and d the thickness of the Helmholtz layer. Thus adsorption of anions ($q_s < 0$) will cause a negative shift in V_{fb} , while cation adsorption ($q_s > 0$) causes a positive shift.

If surface states are present, they may be filled or emptied by either interaction with solution redox couples, by photoprocesses or by charge redistribution within the semiconductor. The overall effect of such filling or emptying of the surface states is to produce surface charge which is a function of the number of surface states and their occupancy. As suggested by eqn (2) the flat-band potential will shift, producing a shift in the relative location of the conduction and valence band edges with respect to a solution redox couple energy level. If the surface state density is sufficiently large, a potential change between semiconductor and solution will result in an almost equal change in $\Delta\phi_H$ (with $\Delta\phi_{sc}$ remaining almost constant). Under these conditions the Fermi level is pinned to the energy level of the surface states (E_{ss}) and the photopotential is independent of V_{redox} (scheme 2):



Scheme 2



When Fermi level pinning exists, photoeffects may be observed for couples whose redox potentials are such that they are apparently located outside of the gap region (based on the V_{fb} value). We have previously suggested⁷ that the high density of surface states can be viewed as a metal overlayer on the semiconductor. This overlayer forms a Schottky barrier with the semiconductor with a height which is independent of the solution redox couple. The overlayer will come into electronic equilibrium with the solution redox couple.

The main point of the argument is that surface charge can cause shifts in the flat-band potential and under some conditions lead to pinning. While we have described these effects in terms of surface states (rather broadly defined), electron injection into the conduction band or hole injection into the valence band (inversion layer formation,¹⁴ or the modification of the electrode surface by the attachment of donor or acceptor molecules¹⁵ can also produce such effects.

We and Wrighton and co-workers⁷⁻⁹ previously gave examples of the Fermi level

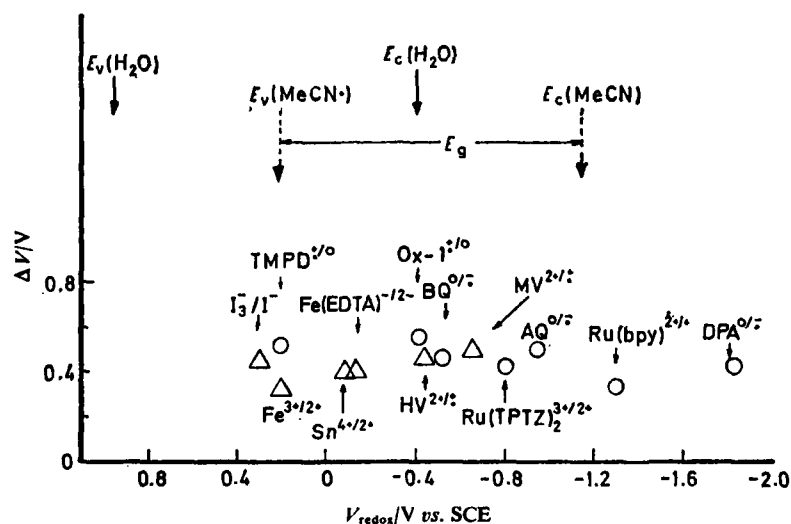


FIG. 1.—Photovoltage as a function of the standard potentials of redox couples. Photovoltage is taken to be the difference in the standard potential of the redox couple and the peak of the photocathodic wave in a cyclic voltammetry scan of the illuminated semiconductor under conditions where photocurrent is limited by diffusion of the redox reagent in the quiet solution (o for n-GaAs/MeCN, 0.1 mol dm⁻³ TBAP); ΔV in p-GaAs/H₂O (symbolized by Δ) is the difference between the standard potential of the redox couple and the onset photopotential of the photocathodic wave. Abbreviations: TMPD = NNN'-tetramethyl-p-phenylene-diamine; Ox-1 = oxazine-1; BQ = benzoquinone; HV = NN'-diheptyl-4,4'-bipyridium; MV = NN'-dimethyl-4,4'-bipyridium; AQ = anthraquinone; bpy = 2,2'-bipyridine; TPTZ = 2,4,6-tripyridyl-s-triazine; DPA = diphenylanthracene; EDTA = ethylenediamine-tetra-acetic acid.

pinning effects at n- and p-GaAs and p-Si in acetonitrile (MeCN) and aqueous solutions. Typical results for n-GaAs in MeCN¹⁶ and p-GaAs in water⁹ are shown in plots of ΔV vs. V_{redox} in Fig. 1. The deviation of the results from eq. (1) and the near independence of ΔV for couples spanning a potential range wider than E_g for GaAs is consistent with the pinning model.

Liquid ammonia cells.—A particularly striking result of Fermi level pinning is observed in electrochemical studies of p-GaAs and p-Si in liquid ammonia^{17,18}.

Typical results are shown in Fig. 2. The cyclic voltammetric scan in $\text{NH}_3/0.1 \text{ M KI}$ at a Pt electrode (curve a) shows that the cathodic current attributable to solvated electron injection starts at -2.4 V [vs. $\text{Ag}/\text{Ag}^+(\text{NH}_3)$], with the collection of electrons occurring on scan reversal.¹⁹ At p-GaAs in the same solution negligible currents are observed in the dark in this potential range. However under steady or chopped illumination with light of energy greater than E_g , a cathodic photocurrent commencing

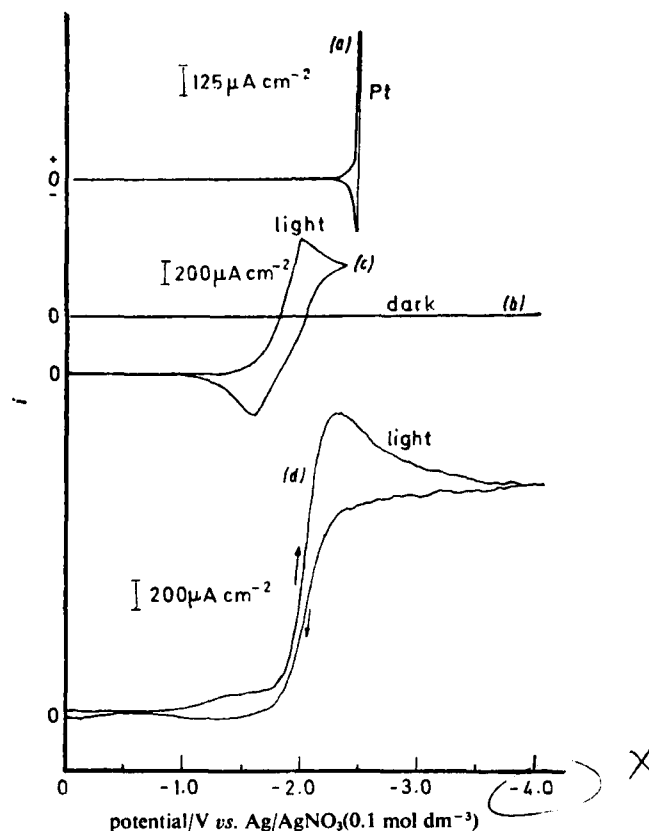


FIG. 2.—(a) Cyclic voltammetric background current for a Pt disc electrode in liquid ammonia. Scan rate 200 mV s^{-1} . (b) A similar scan for p-GaAs and p-Si in the dark. (c) p-GaAs under constant (sun-lamp) illumination. Scan rate 100 mV s^{-1} . (d) p-Si under constant (sunlamp) illumination. Scan rate 100 mV s^{-1} .

at ca -1.5 V is observed (curve c). The blue coloration near the electrode surface during the cathodic pulses clearly indicates that the process is the photoinjection of electrons which occurs at potentials considerably less negative than the reversible value for this process. The V_{fb} -value for n-GaAs determined by capacitance measurements in this solvent (Schottky-Mott plot) is ca -1.2 V . Very similar effects are found for p-Si in liquid ammonia (curve d) where V_{fb} for n-Si in the absence of excess electrons is ca -0.8 V .¹⁸ For both semiconductors, PEC cells can be constructed. The cell p-GaAs/ e_s^- , KI, NH_3/Pt shows an open circuit photovoltage (V_{oc}) of 0.7 V , while the

cell p-Si/e⁻, KI, NH₃/Pt yields $V_{oc} = 0.57$ V. Details of the behaviour of these and several other semiconductors with several redox couples in liquid NH₃ will be published elsewhere.¹⁸

p-WSe₂-NITROBENZENE SYSTEMS

With p-WSe₂ in MeCN photocurrents are also observed for couples located at redox potentials more negative than the conduction band edge [as determined from V_{fb} of p- and n-WSe₂ in 0.1 mol dm⁻³ tetra-n-butyl ammonium perchlorate (TBAP)/MeCN]. The band structure and relevant energy levels are shown in fig. 3. Consider the voltammetric behaviour of nitrobenzene (PhNO₂) shown in fig. 4. The photoelectro-

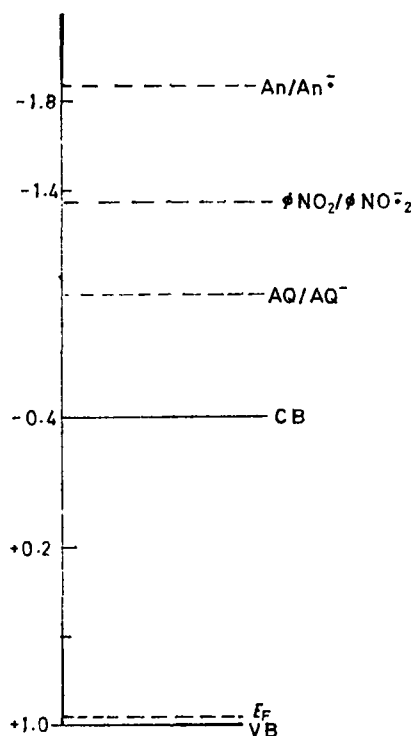


FIG. 3.—Schematic representation of the energetic situation at p-WSe₂/electrolyte interface.

chemical behaviour of PhNO₂ is of interest because highly concentrated solutions of it and its radical anion can be prepared in MeCN, thus minimizing the mass transfer limitations often observed in non-aqueous PEC cells.²⁰ The reduction of PhNO₂ at Pt occurs at -1.33 V *vs.* SCE [curve (a)]. Under illumination with the chopped beam of a He-Ne laser (1.6 mW) no photocurrent is observed at p-WSe₂ even when the potential is swept to -1.0 V [curve (b)] for a solution of 0.2 mol dm⁻³ PhNO₂ in 0.1 mol dm⁻³ TBAP/MeCN. However, if a small amount (ca. 0.095 mol dm⁻³) of PhNO₂ is electrogenerated in the solution at a Pt electrode, a photocurrent is observed at p-WSe₂, beginning at ca. -0.4 V [curve (c)]. Similar effects are observed with anthracene and anthraquinone at p-WSe₂ in MeCN. No cathodic photocurrents are

p-WSe₂
In

0.1 mol

observed unless radical anion is first generated in the solution. We propose that the electrogenerated radical anions inject charge into the p-WSe₂ surface. This negative charge causes a shift in V_{fb} to more negative values until pinning at the potential of the PhNO₂/PhNO₂⁻ is obtained. At this point the conduction band is located at an energy where photogenerated electrons can be injected to produce more PhNO₂⁻.

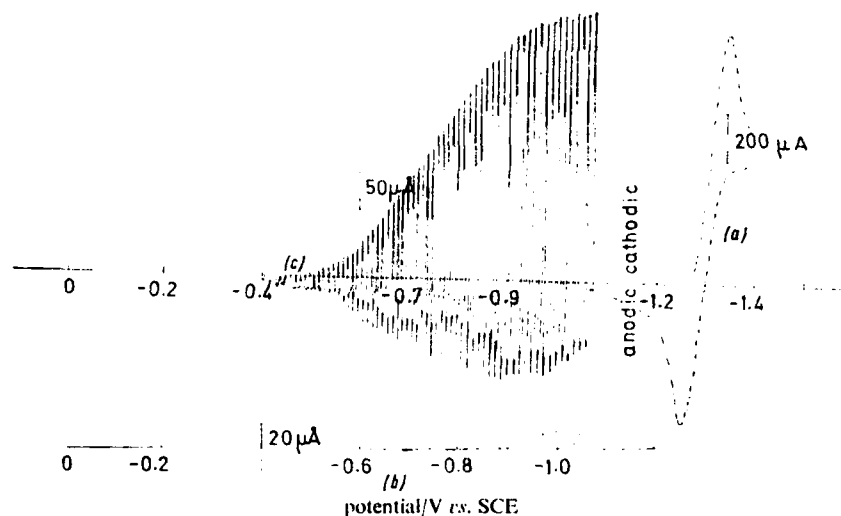


FIG. 4.—(a) Cyclic voltammogram on Pt of the reduction of nitrobenzene. (b) Dark voltammetric curve on p-WSe₂ in acetonitrile solution containing 195 mmol dm⁻³ nitrobenzene. 0.1 mol dm⁻³ TBAP was used as the supporting electrolyte. Scan rate 20 mV s⁻¹. (c) Current-potential characteristic under chopped light on p-WSe₂ in acetonitrile solution containing 0.2 mol dm⁻³ nitrobenzene and 0.095 mmol dm⁻³ nitrobenzene radical anion.

EFFECTS OF SURFACE PRETREATMENTS

There have been many studies demonstrating the importance of semiconductor surface treatment or modification in the electrochemical behaviour.^{15,21-25} For example the surface treatment of n-GaAs with RuCl₃ produced higher efficiencies in PEC cells based on the Se₂²⁻/Se²⁻ redox system.^{21,22} Surface modification by the attachment of electroactive sites can suppress the photoanodic decomposition of the semiconductor lattice.¹⁵ Surface treatments have long been used in the fabrication of solid-state devices. We discuss here two examples of the application of surface treatments to suppress recombination and improve photoresponse.

EFFECT OF Cl⁻ ON n-WSe₂/MeCN SYSTEM

Layered-type transition metal chalcogenides such as MoSe₂ and WSe₂ have been investigated rather extensively.²⁶⁻³⁴ The behaviour of such materials is critically dependent upon the character of the surface. Thus single crystals which show smooth and defect-free van der Waals surfaces (1 *c* axis) (referred to here as "Type S") produce low dark currents and high efficiencies in PEC cells. However, the presence of defects, discontinuities or exposed edges on the van der Waals surface produce electrodes (referred to here as "Type E") which show appreciable dark currents and

poorer photoresponse presumably because these edges provide sites for dark oxidation (at the n-type material) and recombination^{33,34}. We report here experiments on n-WSe₂ in MeCN and the effect of surface treatment on the behaviour of Type E electrodes. Typical behaviour of a Type E n-WSe₂ electrode in MeCN/0.2 mol dm⁻³ TBAP containing thianthrene (TH) is shown in fig. 5. A quasireversible oxidation

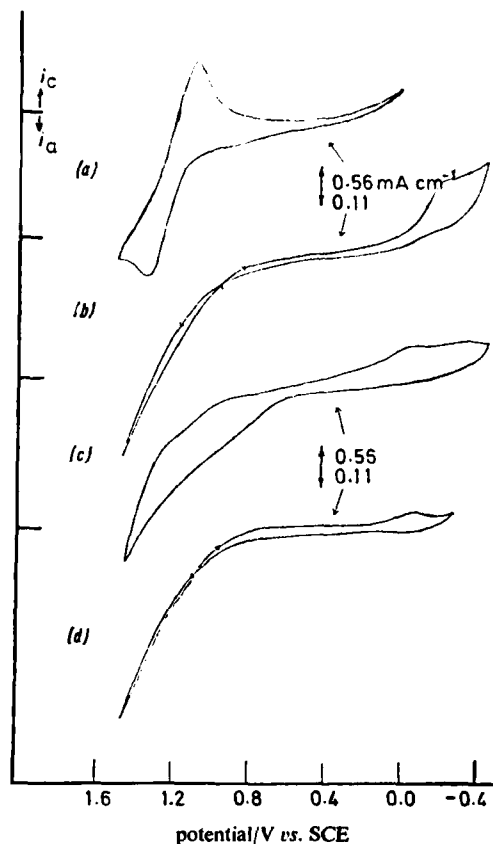


FIG. 5.—Effect of bulk halide on dark currents at Type E n-WSe₂ electrode. (a) 5 mmol dm⁻³ thianthrene (TH); (b) 5 mmol dm⁻³ TH and 15 mmol dm⁻³ TBAl; (c) 5 mmol dm⁻³ TH and 10 mmol dm⁻³ TBABr; (d) 5 mmol dm⁻³ TH and 10 mmol dm⁻³ TMACl. Scan rate 100 mV s⁻¹. 0.2 mol dm⁻³ TBAP as the supporting electrolyte.

wave is shown in the dark [curve (a)]; the charge transfer leading to the oxidation has been attributed to conduction along the edges of the van der Waals planes to surface discontinuities.³⁴ Addition of 5–10 mmol dm⁻³ of I⁻, Br⁻ or Cl⁻ to the solution causes significant decreases of the dark current [curves (b), (c) and (d)]. Addition of Cl⁻ also affects the photo-oxidation of TH at n-WSe₂ (fig. 6); the anodic photocurrent for TH oxidation starts at potentials ca. 0.23 V less positive in solutions containing Cl⁻. Neither Br⁻ nor I⁻ show this effect on the TH photocurrent in MeCN. To demonstrate that this effect results from the interaction of Cl⁻ with the surface discontinuities, the experiment illustrated by fig. 7 was undertaken.

A fresh Type E electrode was prepared and the dark- and photo-oxidation of TH was observed [curves (a) and (b)]. The electrode was then removed and dipped into a MeCN solution of 7.0 mmol dm^{-3} TBACl in the dark without any external electrical connection. After 30 s, the electrode was removed, rinsed thoroughly with MeCN and placed back into the original TH-containing solution. The resulting cyclic voltammograms [curves (c) and (d)] showed an immediate decrease in the dark current and a negative shift (ca. 180 mV) of the onset potential for photocurrent. The maximum photocurrent for TH oxidation increased by ca. 25% following this surface

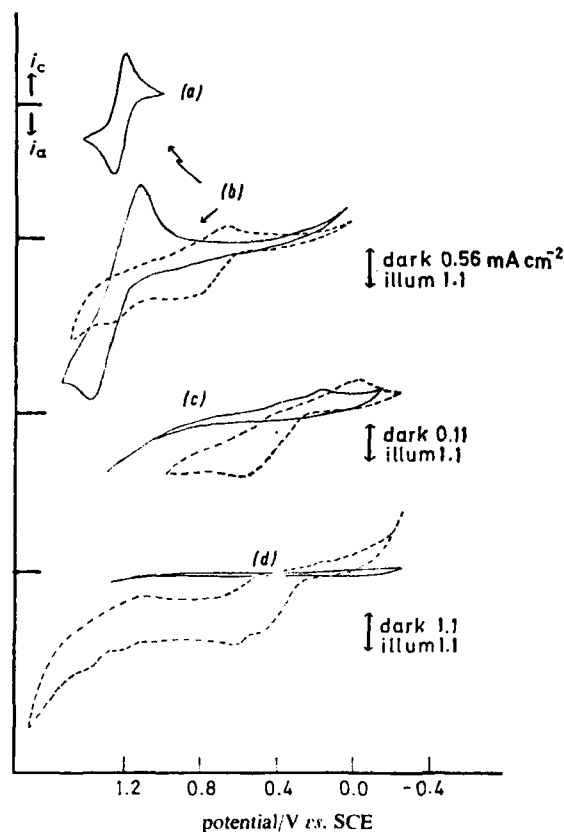


FIG. 6.—Effect of chloride on photo-oxidation of thianthrene; 5 mmol dm^{-3} TH, 10 mmol dm^{-3} TBACl and 0.2 mol dm^{-3} TBAP in acetonitrile solution. Solid lines indicate dark current; broken lines indicate photocurrent; same conditions of TH and Cl^- in mixed solution.

treatment. This improved photocurrent-potential curve remained unchanged for at least 30 min of continuous cycling. When a similar experiment was carried out with a Type S electrode, no changes in the dark oxidation current (which was negligible) or the photocurrent was found by a Cl^- pretreatment. Note that the decrease in dark current for the Type E electrode upon treatment with Cl^- takes place without any possibility of photo-oxidation occurring during the exposure of the electrode to Cl^- so that the formation of a light-induced complex between the electrode and Cl^- is

- (a) TH at platinum; (b) TH only; (c) 10 mM TEACl;
(d) 5 mM TH and 10 mM TEACl.

insert

unlikely. The observed effect can be ascribed to interactions of the Cl^- with surface discontinuities leading to modification or passivation of these sites. Similar shifts in photopotential of redox couples in aqueous media have been found by Tributsch and co-workers^{26,30} by the addition of the I^-/I_2 couple.

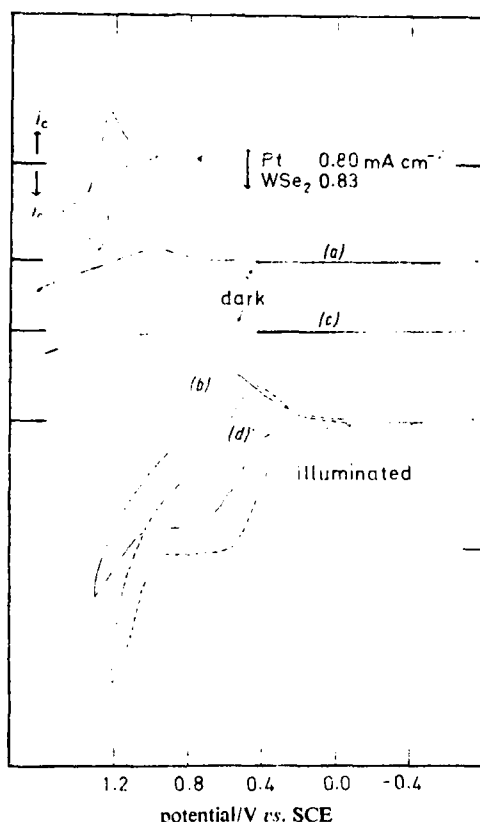


FIG. 7.—Effect of dipping Type E n-WSe₂ electrode into 7 mmol dm⁻³ TEACl solution. (a) Dark oxidation of 5 mmol dm⁻³ TH on untreated electrode. (b) Photo-oxidation of 5 mmol dm⁻³ TH on untreated electrode. (c) Dark oxidation of TH after Cl⁻ treatment. (d) Photocurrent after Cl⁻ treatment.

HNO₃ ETCHING OF p-GaAs

Surface pretreatment also affected the dark and photoresponses of a p-GaAs electrode. The behaviour of an HCl-etched p-GaAs single crystal electrode in aqueous solution of *N,N'*-dimethyl-4,4'-bipyridinium (or methyl viologen, MV^{2+}) has been reported.¹⁰ When a p-GaAs crystal (100 face) was polished first with SiC paper and then with 0.5 μm alumina powder on felt until a mirror-like surface is obtained and then used as an electrode in the MV^{2+} medium, the dark i - V curves were practically the same as those observed at a metal electrode and no photoresponse was obtained (fig. 8) [curve (a)]. A scanning electron micrograph of this surface is shown in fig. 9 (a). X-ray fluorescence measurements of this electrode surface show *K*-series peaks for

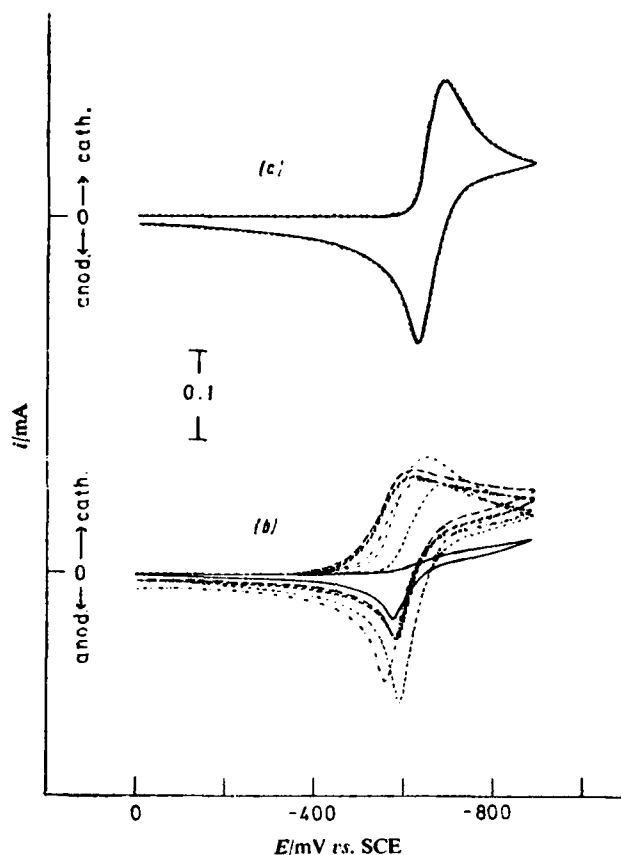


FIG. 8.—Cyclic voltammograms of methyl viologen (MV^{2+}) in $0.5 \text{ mol dm}^{-3} \text{ Na}_2\text{SO}_4$ aqueous solution on p-GaAs electrode. Scan rate 50 mV s^{-1} . (a) On alumina polished electrode: (—) in the dark; (---) under illumination. (b) On electrodes etched with $3.7 \text{ mol dm}^{-3} \text{ HNO}_3$ acid: (—) in the dark; under illumination: (---) 15 s etching, (---) 30 s etching, (---) 1 min etching, (---) 2 min etching, (---) 5 min etching, and (---) 10 min etching.

Ga (9.25 keV) and As (10.54 keV) with the Ga peaks larger than the ones for As. The effect of etching the electrode with $3.7 \text{ mol dm}^{-3} \text{ HNO}_3$ for various lengths of time is illustrated in fig. 8 and 9. Even a very brief immersion ($\sim 15 \text{ s}$) causes a significant decrease in the dark current and improved photoresponse [curve (b)]. Continued etching for times up to 10 min showed constant improvement in the photoresponse and changes in the electrode surface. X-ray fluorescence measurements show a continual increase in the ratio of As/Ga peak heights with the electrode which has been etched for 10 min yielding almost no Ga peak. The high As levels appear to be associated with the crystallites which are formed on the surface during etching, since X-ray fluorescence measurements on the exposed flat surfaces of the electrodes in fig. 9 (b), (c) and (d) continue to show a As/Ga peak height ratio close to that for the polished electrode. Etching with $0.9 \text{ mol dm}^{-3} \text{ HNO}_3$ for periods of up to 80 min was ineffective in improving the dark current or photoresponse of the p-GaAs electrode and an electrode so treated showed behaviour similar to that in fig. 8(a).

These results can be interpreted in terms of the existence of a very disturbed surface with a high population of states formed by the polishing. Grinding or polishing of semiconductors is known to induce states in the gap.³⁵ The material then shows a metallic behaviour. Etching of the surface removes the damaged layer and may also cause passivation of surface states. Recent experiments have suggested that deposition of small amounts of metal on the electrode surface can produce similar effects.

CONCLUSIONS

The results here, as well as numerous past studies of junctions to semiconductors, demonstrate the importance of surface states in the interpretation of photoelectrochemical behaviour. For semiconductors where pinning is observed these effects allow photoprocesses to occur which would not be predicted from V_{fb}^2 measurements. This has been demonstrated here for p-type materials where the photoreduction of couples with very negative redox potentials is found. In principle a similar effect should be possible at n-type semiconductors and couples with very positive redox levels. However in this case hole injection into the valence band with decomposition of the semiconductor may occur.

Surface states may also play an important role in the catalysis of surface chemical reactions in a manner similar to that seen in electrochemical reactions at metal electrodes. For example the photoproduction of hydrogen³⁶ probably involves as a first step the formation of a hydrogen atom ($H\cdot$). Since the potential for this reaction in bulk aqueous solution is very negative (ca. -2.1 V vs. NHE), production of H_2 will probably require the presence of surface sites which will adsorb $H\cdot$ quite strongly and also promote their combination. Similarly adsorption of hydroxyl radicals is required for O_2 production.

An understanding of the chemical and physical nature of the surface states on a molecular level is clearly needed. Such an understanding is only now beginning to emerge in studies of semiconductor surfaces in a high vacuum environment. For example the pinning of GaSb, GaAs and InP surface at the same level by submonolayer coverage of metals and oxygen has recently been reported and ascribed to the induced formation of defect levels by the adatoms.⁴ Induced defect levels and impurity levels may similarly be formed at the semiconductor-liquid interfaces (i.e., the surfaces may change in the act of forming the junction), but *in situ* molecular or microscopic characterization of these will be difficult. A general observation from all of these results is that the character of the semiconductor-liquid junction is very specific for the particular conditions existing at that junction and the method of pretreatment of the surface. It will be very difficult therefore to provide a general theoretical model which will allow prediction of the interface properties simply from the characteristics of semiconductor and solution phases. Similar opinions have been expressed concerning the metal-semiconductor Schottky barrier.³⁶

The support of this research by the National Science Foundation, the Solar Energy Research Institute and the Office of Naval Research is gratefully acknowledged. We are indebted to Dr. Richard Malpas for the liquid ammonia measurements. We also acknowledge a fellowship to A. S. G. by the Consejo Nacional de Investigaciones Científicas y Técnicas de la Republica Argentina.

¹ W. Schottky, *Naturwiss.*, 1938, 26, 843.

² N. F. Mott, *Proc. Cambridge Phil. Soc.*, 1938, 34, 568.

³ J. Bardeen, *Phys. Rev.*, 1947, 71, 717.

- ⁴ W. E. Spicer, I. Lindau, P. Skeath, C. Y. Su and P. Chye, *Phys. Rev. Letters*, 1980, **44**, 420.
- ⁵ J. O. McCaldin, T. C. McGill and C. A. Mead, *Phys. Rev. Letters*, 1976, **36**, 56.
- ⁶ M. Green, *J. Chem. Phys.*, 1959, **31**, 200.
- ⁷ A. J. Bard, A. B. Bocarsly, F. R. Fan, E. G. Walton and M. S. Wrighton, *J. Amer. Chem. Soc.*, 1980, *in press*.
- ⁸ A. B. Bocarsly, D. C. Bookbinder, R. N. Dominey, N. S. Lewis and M. S. Wrighton, *J. Amer. Chem. Soc.*, 1980, *in press*.
- ⁹ F. R. Fan and A. J. Bard, *J. Amer. Chem. Soc.*, 1980, *in press*.
- ¹⁰ F.-R. F. Fan, B. Reichman and A. J. Bard, *J. Amer. Chem. Soc.*, 1980, **102**, 1488.
- ¹¹ F.-R. F. Fan, H. S. White, B. Wheeler and A. J. Bard, *J. Electrochem. Soc.*, 1980, **127**, 518.
- ¹² R. Memming, in *Electroanalytical Chemistry*, ed. A. J. Bard (Dekker, New York, 1979), pp. 1-84.
- ¹³ H. Gerischer, in *Physical Chemistry—An Advanced Treatise*, ed. H. Eyring, D. Henderson, W. Jost (Academic Press, New York, 1970), pp. 463-542.
- ¹⁴ W. Kautek and H. Gerischer, personal communication.
- ¹⁵ J. M. Bolts, A. B. Bocarsly, M. C. Palazzotto, E. G. Walton, N. S. Lewis and M. S. Wrighton, *J. Amer. Chem. Soc.*, 1979, **101**, 1378 and references therein.
- ¹⁶ P. A. Kohl and A. J. Bard, *J. Electrochem. Soc.*, 1979, **126**, 59.
- ¹⁷ R. E. Malpas, K. Itaya and A. J. Bard, *J. Amer. Chem. Soc.*, 1979, **101**, 2535.
- ¹⁸ R. E. Malpas and A. J. Bard, manuscript in preparation.
- ¹⁹ T. Teherani, K. Itaya and A. J. Bard, *Nouv. J. Chem.*, 1978, **2**, 481.
- ²⁰ P. A. Kohl and A. J. Bard, *J. Electrochem. Soc.*, 1979, **126**, 603.
- ²¹ A. Heller, B. A. Parkinson and B. Miller, *Appl. Phys. Letters*, 1978, **33**, 521.
- ²² B. A. Parkinson, A. Heller and B. Miller, *J. Electrochem. Soc.*, 1979, **126**, 954.
- ²³ W. H. Brattain and P. J. Boddy, *Surface Sci.*, 1966, **4**, 18.
- ²⁴ H. Gerischer, *N.B.S. Spec. Pub.*, 1975, **455**, 1.
- ²⁵ S. R. Morrison, *The Chemical Physics of Surfaces* (Plenum Press, New York, 1977).
- ²⁶ H. Tributsch, *J. Electrochem. Soc.*, 1978, **125**, 1086.
- ²⁷ H. Tributsch and J. C. Bannett, *J. Electroanal. Chem.*, 1977, **81**, 91.
- ²⁸ H. Tributsch, *Ber. Bunsenges. phys. Chem.*, 1977, **81**, 361.
- ²⁹ H. Tributsch, *Ber. Bunsenges. phys. Chem.*, 1978, **82**, 169.
- ³⁰ H. Tributsch, H. Gerischer, C. Clemen and E. Bucher, *Ber. Bunsenges. phys. Chem.*, 1979, **83**, 655.
- ³¹ L. F. Schneemeyer and M. S. Wrighton, *J. Amer. Chem. Soc.*, 1979, **101**, 6496.
- ³² F.-R. Fan, H. S. White, B. Wheeler, and A. J. Bard, *J. Amer. Chem. Soc.*, *submitted*; *J. Electrochem. Soc.*, 1980, **127**, 518.
- ³³ H. J. Lewerenz, A. Heller and F. J. Disalvo, *J. Amer. Chem. Soc.*, 1980, **102**, 1877.
- ³⁴ W. Kautek, H. Gerischer and H. Tributsch, *Ber. Bunsenges. phys. Chem.*, 1979, **83**, 1000.
- ³⁵ A. Aresti, P. Manca and A. Spiga, *Chem. phys. Letters*, 1979, **63**, 139 and references therein.
- ³⁶ G. Margaritondo, J. E. Rowe and S. B. Christman, *Phys. Rev.*, 1976, **14B**, 5396.

102, 3671

102, 3683

102, 3677

1980, 102, 5142

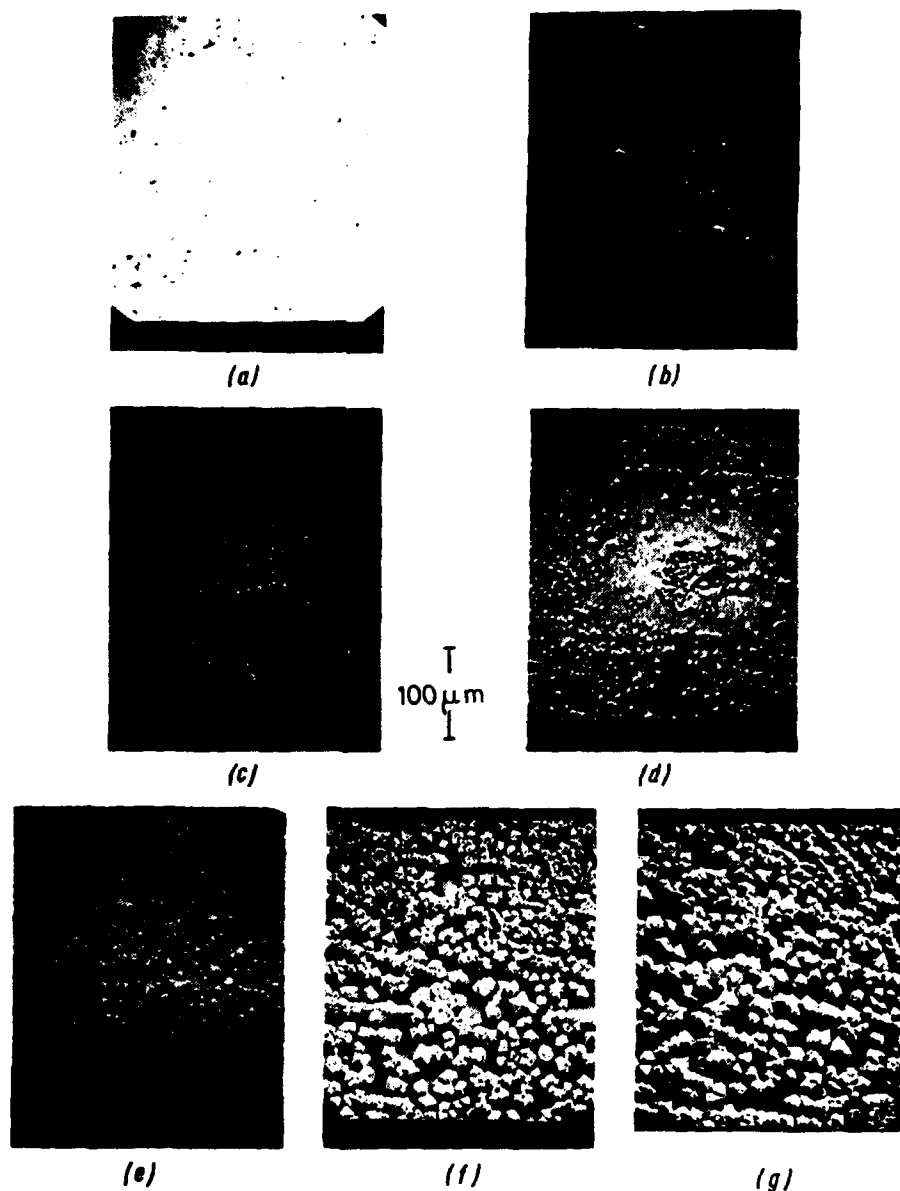


FIG. 9.—Scanning electron micrographs for the electrode surface with different treatments: (a) polished with alumina; (b) etched in $3.7 \text{ mol dm}^{-3} \text{ HNO}_3$ for 15 s; (c) etched in 3.7 mol dm^{-3} for 30 s; (d) 1 min etching; (e) 2 min etching; (f) 5 min etching; (g) 10 min etching.

7.9

7.9

TECHNICAL REPORT DISTRIBUTION LIST, GEN

	<u>No. Copies</u>		<u>No. Copies</u>
Office of Naval Research Attn: Code 472 800 North Quincy Street Arlington, Virginia 22217	2	U.S. Army Research Office Attn: CRD-AA-IP P.O. Box 1211 Research Triangle Park, N.C. 27709	1
ONR Branch Office Attn: Dr. George Sandoz 536 S. Clark Street Chicago, Illinois 60605	1	Naval Ocean Systems Center Attn: Mr. Joe McCartney San Diego, California 92152	1
ONR Area Office Attn: Scientific Dept. 715 Broadway New York, New York 10003	1	Naval Weapons Center Attn: Dr. A. E. Anster, Chemistry Division China Lake, California 93555	1
ONR Western Regional Office 1030 East Green Street Pasadena, California 91106	1	Naval Civil Engineering Laboratory Attn: Dr. R. W. Drisko Port Hueneme, California 93401	1
ONR Eastern/Central Regional Office Attn: Dr. L. H. Peebles Building 114, Section D 666 Summer Street Boston, Massachusetts 02210	1	Department of Physics & Chemistry Naval Postgraduate School Monterey, California 93940	1
Director, Naval Research Laboratory Attn: Code 6100 Washington, D.C. 20390	1	Dr. A. L. Slaifosky Scientific Advisor Commandant of the Marine Corps (Code RD-1) Washington, D.C. 20380	1
The Assistant Secretary of the Navy (RE&S) Department of the Navy Room 4E736, Pentagon Washington, D.C. 20350	1	Office of Naval Research Attn: Dr. Richard S. Miller 800 N. Quincy Street Arlington, Virginia 22217	1
Commander, Naval Air Systems Command Attn: Code 310C (H. Rosenwasser) Department of the Navy Washington, D.C. 20360	1	Naval Ship Research and Development Center Attn: Dr. G. Bosmajian, Applied Chemistry Division Annapolis, Maryland 21401	1
Defense Technical Information Center Building 5, Cameron Station Alexandria, Virginia 22314	12	Naval Ocean Systems Center Attn: Dr. S. Yamamoto, Marine Sciences Division San Diego, California 91232	1
Dr. Fred Saalfeld Chemistry Division, Code 6100 Naval Research Laboratory Washington, D.C. 20375	1	Mr. John Boyle Materials Branch Naval Ship Engineering Center Philadelphia, Pennsylvania 19112	1

TECHNICAL REPORT DISTRIBUTION LIST, GENNo.
Copies

Dr. Rudolph J. Marcus
Office of Naval Research
Scientific Liaison Group
American Embassy
APO San Francisco 96503

1

Mr. James Kelley
DTNSRDC Code 2803
Annapolis, Maryland 21402

1

TECHNICAL REPORT DISTRIBUTION LIST, 359

	<u>No. Copies</u>		<u>No. Copies</u>
Dr. Paul Delahay Department of Chemistry New York University New York, New York 10003	1	Dr. P. J. Hendra Department of Chemistry University of Southampton Southampton SO9 5NH United Kingdom	1
Dr. E. Yeager Department of Chemistry Case Western Reserve University Cleveland, Ohio 41106	1	Dr. Sam Perone Department of Chemistry Purdue University West Lafayette, Indiana 47907	1
Dr. D. N. Bennion Department of Chemical Engineering Brigham Young University Provo, Utah 84602	1	Dr. Royce W. Murray Department of Chemistry University of North Carolina Chapel Hill, North Carolina 27514	1
Dr. R. A. Marcus Department of Chemistry California Institute of Technology Pasadena, California 91125	1	Naval Ocean Systems Center Attn: Technical Library San Diego, California 92152	1
Dr. J. J. Auborn Bell Laboratories Murray Hill, New Jersey 07974	1	Dr. C. E. Mueller The Electrochemistry Branch Materials Division, Research & Technology Department Naval Surface Weapons Center White Oak Laboratory Silver Spring, Maryland 20910	1
Dr. Adam Heller Bell Laboratories Murray Hill, New Jersey 07974	1	Dr. G. Goodman Globe-Union Incorporated 5757 North Green Bay Avenue Milwaukee, Wisconsin 53201	1
Dr. T. Katan Lockheed Missiles & Space Co, Inc. P.O. Box 504 Sunnyvale, California 94088	1	Dr. J. Boechler Electrochimica Corporation Attention: Technical Library 2485 Charleston Road Mountain View, California 94040	1
Dr. Joseph Singer, Code 302-1 NASA-Lewis 21000 Brookpark Road Cleveland, Ohio 44135	1	Dr. P. P. Schmidt Department of Chemistry Oakland University Rochester, Michigan 48063	1
Dr. B. Brummer EIC Incorporated 55 Chapel Street Newton, Massachusetts 02158	1	Dr. H. Richtol Chemistry Department Rensselaer Polytechnic Institute Troy, New York 12181	1
Library P. R. Mallory and Company, Inc. Northwest Industrial Park Burlington, Massachusetts 01803	1		

TECHNICAL REPORT DISTRIBUTION LIST, 359

	<u>No.</u> <u>Copies</u>		<u>No.</u> <u>Copies</u>
Dr. A. B. Ellis Chemistry Department University of Wisconsin Madison, Wisconsin 53706	1	Dr. R. P. Van Duyne Department of Chemistry Northwestern University Evanston, Illinois 60201	1
Dr. M. Wrighton Chemistry Department Massachusetts Institute of Technology Cambridge, Massachusetts 02139	1	Dr. B. Stanley Pons Department of Chemistry University of Alberta Edmonton, Alberta CANADA T6C 2G2	1
Larry F. Plew Naval Weapons Support Center Code 30735, Building 2906 Crane, Indiana 47522	1	Dr. Michael J. Weaver Department of Chemistry Michigan State University East Lansing, Michigan 48824	1
S. Ruby DOF (STOR) 600 E Street Washington, D.C. 20545	1	Dr. R. David Rauh EIC Corporation 55 Chapel Street Newton, Massachusetts 02158	1
Dr. Aaron Wold Brown University Department of Chemistry Providence, Rhode Island 02192	1	Dr. J. David Margerum Research Laboratories Division Hughes Aircraft Company 3011 Malibu Canyon Road Malibu, California 90265	1
Dr. R. C. Chudacek McGraw-Edison Company Edison Battery Division Post Office Box 28 Bloomfield, New Jersey 07003	1	Dr. Martin Fleischmann Department of Chemistry University of Southampton Southampton 509 5NH England	1
Dr. A. J. Bard University of Texas Department of Chemistry Austin, Texas 78712	1	Dr. Janet Osteryoung Department of Chemistry State University of New York at Buffalo Buffalo, New York 14214	1
Dr. M. M. Nicholson Electronics Research Center Rockwell International 3370 Miraloma Avenue Anaheim, California	1	Dr. R. A. Osteryoung Department of Chemistry State University of New York at Buffalo Buffalo, New York 14214	1
Dr. Donald W. Ernst Naval Surface Weapons Center Code R-33 White Oak Laboratory Silver Spring, Maryland 20910	1	Mr. James R. Moden Naval Underwater Systems Center Code 3632 Newport, Rhode Island 02840	1

TECHNICAL REPORT DISTRIBUTION LIST, 359

	<u>No.</u> <u>Copies</u>		<u>No.</u> <u>Copies</u>
Dr. R. Nowak Naval Research Laboratory Code 6130 Washington, D.C. 20375	1	Dr. John Kincaid Department of the Navy Strategic Systems Project Office Room 901 Washington, DC 20376	1
Dr. John F. Houlihan Shenango Valley Campus Pennsylvania State University Sharon, Pennsylvania 16146	1	M. L. Robertson Manager, Electrochemical Power Sonics Division Naval Weapons Support Center Crane, Indiana 47522	1
Dr. M. G. Sceats Department of Chemistry University of Rochester Rochester, New York 14627	1	Dr. Elton Cairns Energy & Environment Division Lawrence Berkeley Laboratory University of California Berkeley, California 94720	1
Dr. D. F. Shriver Department of Chemistry Northwestern University Evanston, Illinois 60201	1	Dr. Bernard Spielvogel U.S. Army Research Office P.O. Box 12211 Research Triangle Park, NC 27709	1
Dr. D. H. Whitmore Department of Materials Science Northwestern University Evanston, Illinois 60201	1	Dr. Denton Elliott Air Force Office of Scientific Research Bldg. 104 Bolling AFB Washington, DC 20332	1
Dr. Alan Bewick Department of Chemistry The University Southampton, SO9 5NH England	1		
Dr. A. Himy NAVSEA-5433 NC #4 2541 Jefferson Davis Highway Arlington, Virginia 20362	1		

MED
8